	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	1662	screw and chip and case and substrate	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:48			0
2	BRS	L2	193	L1 and (clip or pawls or claw or prong)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 11:25			0
3	BRS	L3	849	L1 and (clip or pawls or claw or prong or (spring adj connector) or spring)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:08			0
4	BRS	L4	196	L1 and (clip or pawls or claw or prong or (spring adj connector))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 14:03			0
5	BRS	L5	143	L1 and (clip or pawls)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:04			0
6	BRS	L6	38	L1 and pawls	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:04			0
7	BRS	L7	1232	screw and chip and (housing or package) and substrate	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:08			0
8	BRS	L8	674	L7 and (clip or finger or pawls or claw or prong or (spring adj connector) or spring)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:46			0
9	BRS	L9	144	(wire adj bond) and (chip near substrate) and (cap or cover or (control adj substrate))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:54			0

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	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
10	BRS	L10	24	L9 and (removable or detachable)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:50			0
11	BRS	L11	140	L9 and (case or hous$ or package or plate)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:58		Truncation Overflow. Return string from Server is: 5`2265060	1
12	BRS	L12	852	power adj chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 12:58			0
13	BRS	L13	1	L12 and (control adj substrate)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:13			0
14	BRS	L14	3144	control adj substrate	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:02			0
15	BRS	L15	16	L14 and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:04			0
16	BRS	L16	861	257/718.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:06			0
17	BRS	L17	162	257/500.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:06			0
18	BRS	L18	0	L17 and screw	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:13			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
19	BRS	L19	1046	257/678.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:14			0
20	BRS	L20	28	L19 and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:17			0
21	BRS	L21	38	L19 and screw	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:22			0
22	BRS	L22	3	L19 and pawl	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:25			0
23	BRS	L23	508	257/719.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:25			0
24	BRS	L24	228	257/719.ccls. and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:31			0
25	BRS	L25	679	257/686.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:34			0
26	BRS	L26	753	257/698.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:35			0
27	BRS	L27	50	L26 and chip and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:37			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
28	BRS	L28	46	L25 and chip and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:38			0
29	BRS	L29	2	257/688.ccls. and chip and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:39			0
30	BRS	L30	75	257/688.ccls. and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:41			0
31	BRS	L31	307	257/696.ccls. and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:47			0
32	BRS	L32	367	screw and chip and case and substrate and (removable or detachable)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:56			0
33	BRS	L33	8163	(case or housing or packade) near (removable or detachable)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:58			0
34	BRS	L34	1	on adj board adj (semiconductor or chip)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 13:59			0
35	BRS	L35	1595	(clip or pawls or claw or prong or (spring adj connector)) near (electrodes or terminal or lead)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 14:06			0
36	BRS	L36	8	L35 and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 14:07			0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
BRS	L37	152	L35 and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 14:08			0

37

#	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1	BRS	380	257/341.ccls.	USPAT	2001/02/13 18:14		
2	BRS	466	257/341.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:18		
3	BRS	0	257/341.ccls. and pawls	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:18		
4	BRS	0	257/341.ccls. and (power adj cihp)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:18		
5	BRS	83	257/341.ccls. and plate	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:21		
6	BRS	554	257/727.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:57		
7	BRS	0	257/727.ccls. and (on adj board)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:24		
8	BRS	0	257/727.ccls. and (ocntrol adj substrate)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:24		
9	BRS	0	257/727.ccls. and (control adj substrate)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:25		
10	BRS	137	257/727.ccls. and (IGBT or MOsfet or mos or power)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:49		
11	BRS	54	(257/727.ccls. and (IGBT or MOsfet or mos or power)) and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:36		
12	BRS	0	257/72.ccls. and 257/735.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:36		
13	BRS	2	257/727.ccls. and 257/735.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:37		
14	BRS	149	257/727.ccls. and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:49		
15	BRS	83	257/727.ccls. and chip and substrate	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 18:49		
16	BRS	212	257/727.ccls. and spring	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 19:16		
17	BRS	319	257/735.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 20:50		
18	BRS	1063	257/724.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 19:35		
19	BRS	618	257/72.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 19:36		
20	BRS	1039	257/723.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 19:36		
21	BRS	667	257/723.ccls. and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 19:36		
22	BRS	303	(257/723.ccls. and chip) and case	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 19:50	/	
23	BRS	570	257/724.ccls. and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 20:24		
24	BRS	271	257/724.ccls. and chip and power	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 19:52		
25	BRS	0	257/691.ccls	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 20:25		
26	BRS	633	257/691.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 20:25		
27	BRS	409	257/707.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/13 21:12		
28	BRS	737	257/734.ccls.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 11:18		

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Errors	
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	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	IS&R	L1	0	("chip and pawl").PN.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 18:29			0
2	BRS	L2	752	chip and pawl	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 18:33			0
3	BRS	L3	173	chip and pawl and substrate	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 18:42			0
4	BRS	L4	27667	(case or housing or package) and pawl	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 18:43			0
5	BRS	L5	593	L4 and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 18:44			0
6	BRS	L6	1	L2 and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:01			0
7	BRS	L7	152	screw and (wire adj bond)and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:04			0
8	BRS	L8	11829	screw and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:05			0
9	BRS	L9	36	screw and chip and (control near(substrate or (ciruit adj board)))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:18			0
10	BRS	L10	1		USPAT	2001/02/14 19:10			0
11	BRS	L11	1		USPAT	2001/02/14 19:10			0

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	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
12	BRS	L12	1		USPAT	2001/02/14 19:10			0
13	BRS	L13	1		USPAT	2001/02/14 19:11			0
14	BRS	L14	5244	power and chip and screw	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:18			0
15	BRS	L15	54	L14 and (screw near (case or wall or board))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:51			0
16	BRS	L17	320	L16 and chip	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:55			0
17	BRS	L18	3	L17 and (wire adj bond)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 19:53			0
18	BRS	L19	34	L17 and (screw or pawl)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 20:00			0
19	BRS	L20	109	Igbt and screw	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/14 20:00			0